

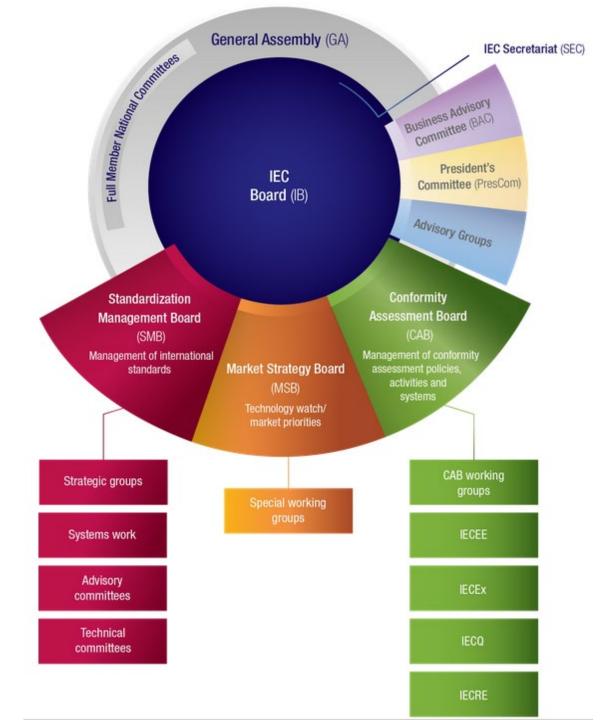
## IEC Structure

## Core principles:

- Transparency & Accountability
- Performance management
- Diversity

https://www.iec.ch/management-structure





# **IEC** in Figures (2022-10)

World's leading provider of International Standards and Conformity Assessment Systems in Electrotechnology

174 Countries

62 Full Members

26 Associate Members

86 Affiliates

214 Committees

(111 TCs, 103 SCs, 11 TC 100 TAs, 4 PCs, 6 ACs, 24 JTC1 SCs, 7 SyCs)

https://www.iec.ch/what-we-do/facts-figures

10 000+ Publications

4 Conformity Assessment Systems

20 000+ Experts



## **IEC TC47 Structure**

#### **TC47 Semiconductor Devices**

SC 47A

(Integrated Circuits)

WG 2 - Modelling of integrated circuits for behavioural simulation related to electromagnetic

WG 7 Heterogeneous ICs

compatibility

WG 9 - Test procedures and measurement methods for EMC in integrated circuits **SC 47D** 

(Semiconductor Device Packaging)

WG 1 - Package outlines

WG 2 - Terms, definitions, practices and procedures and measuring methods for mechanical standardization **SC 47E** 

(Discrete Semiconductor Devices)

WG 1 -Semiconductor sensors

WG 2 - Microwave devices

WG 3 - Power devices

WG 4 - Optocouplers, photocoplers and solid state optorelays

WG 8 - Magnetic and capacitive couplers for basic and reinforced isolation

WG 9 - Laser diodes, LEDs, PDs and APDs SC 47F

WG 1 -

Terminologies and generic specification for microelectromechanical systems

WG 2 -Charact

Characterizations and testing methods of materials and structures for microelectromechan ical systems

WG 3 - Microelectromechanical devices and packaging

MT 1 - Maintenance team for the published ISs under SC47F/WG2 WG 1 - Terminology

WG 2 - Semiconductor Device Test Methods and Guidelines -Mechanical, Climatic and Storage

Merged with WG3

WG 5 - Wafer Level Reliability for semiconductor devices

WG 6 – Incubating Working Group (IWG)

WG 7 - Semiconductor devices for energy conversion and transfer

WG 8 - Wide bandgap technologies – Power electronic conversion

New WG



## **IEC TC47 Liaisons**

#### Internal IEC Liaison

• TC 56 Dependability (Liaison officer: Mr. Nicholas E.F. Lycoudes) Electronics assembly technology (Liaison officer: Mr. Jim Lynch) • TC 91 Electrostatics (Liaison officer: Mr. Jim Lynch) • TC 101 Process management for avionics (Liaison officer: Mr. Nicholas E.F. Lycoudes) • TC 107 Electronic display devices (Liaison officer: Mr. Sung Hoon Choa) • TC 110 Environmental standardization for electrical and electronic products and systems • TC 111 (Liaison officer: Mr. Stephen Tisdale) Nanotechnology for electrotechnical products and systems • TC 113 Printed Electronics (Liaison officer: Mr. Hojun Ryu) • TC 119 Wearable Electronic Devices and Technologies (Liaison officer: Mr. Deok-kee Kim) • TC124

#### Liaison with ISO

• ISO TC22/SC31 Data communication (Liaison officer: Mr. Werner Berns)

#### Liaison C

• EIA: WG 1, WG 2, WG 3 and WG 5 (Liaison officer: Mr. Nicholas E.F. Lycoudes)



### **IEC SC47E Liaisons**

#### Internal IEC Liaison

- TC 34 Lighting (Liaison officers: Mr. Andreas Scholtz, Mr. Alexander Wilm)
- SC 23A Electric light sources (Liaison officer: Mr. Naokage Kishimoto)
- TC 49 Piezoelectric, dielectric and electrostatic devices
- TC 91 Electronics assembly technology
- TC 108 Safety of electronic equipment within the field of audio/video

### (Liaison officer: Mr. Hojun Ryu)

#### Liaison with ISO

• ISO TC172 SC9 Laser and electro-optical system



### **IEC TC47 P/O Member Countries**

- TC47: 16 Participating and 19 Observing members (2022-11-03) Requirements to get an approval for NWIP (new work item)
  - >=4 experts nominated by different NCs (criteria for 16 P-members)
  - >=66.7% of voting P-members vote in favour

Country	<b>Country Code</b>	P/O Status
Austria	AT	P-Member
Belgium	BE	P-Member
Switzerland	CH	P-Member
China	CN	P-Member
Germany	DE	P-Member
France	FR	P-Member
United Kingdom	GB	P-Member
Ireland	IE	P-Member
Israel	IL	P-Member
Italy	IT	P-Member
Japan	JP	P-Member
Korea, Republic of	KR	P-Member
Pakistan	PK	P-Member
Russian Federation	RU	P-Member
Singapore	SG	P-Member
United States of America	US	P-Member

Country	<b>Country Code</b>	P/O Status
Bulgaria	BG	O-Member
Belarus	BY	O-Member
Czech Republic	CZ	O-Member
Denmark	DK	O-Member
Spain	ES	O-Member
Finland	FI	O-Member
Hungary	HU	O-Member
India	IN	O-Member
Iran	IR	O-Member
Netherlands	NL	O-Member
Norway	NO	O-Member
Philippines, Rep. of the	PH	O-Member
Poland	PL	O-Member
Romania	RO	O-Member
Serbia	RS	O-Member
Sweden	SE	O-Member
Thailand	TH	O-Member
Turkey	TR	O-Member
Ukraine	UA	O-Member



### **New Ad-Hoc WG in TC47**

From Robert Mitchell (Chairmen of TC47):

"TC47 has voted and agreed at the 2022 Plenary meeting to establish an ad-hoc group to address these issues. Language, terminology and scope of the group is under discussion."

- This new working group shall align with EU "Trusted Chips" and related world wide activities.
- Plan to accept not only representatives from National Committees (NC, but also representatives from companies.



